

Magnetic Field Imaging Magma

EUFANET meeting October 8, 2003



Magnetic Field Imaging

- Imaging approaches that Neocera is presently using
 - SQUID
 - Fibre/SQUID
 - Magnetoresistance
- Application space
 - Boards Packages (Flip-chip, stacked die, etc.) ICs (wafers)
 - Shorts Resistive Opens Current leakage Logic failures
 - Resolution from 10s of microns to sub-micron
 - Current sensitivity down to 100s of nA
 - Working distances from > 1mm to < 100 nm



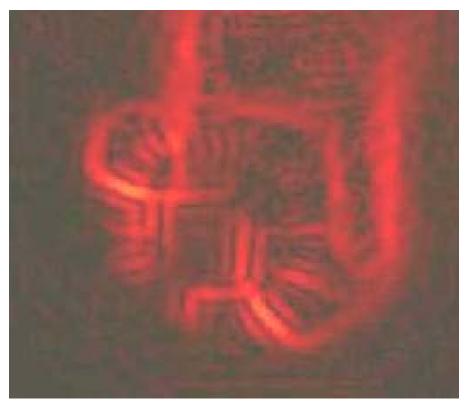
System Platform

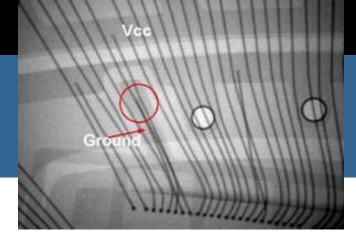




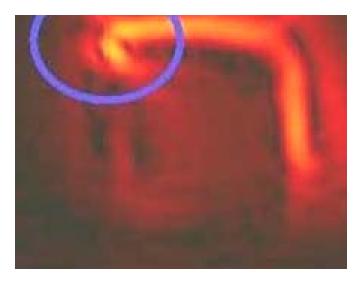
SQUID at Package-Level (wire bond)

Good Part





Bad Part



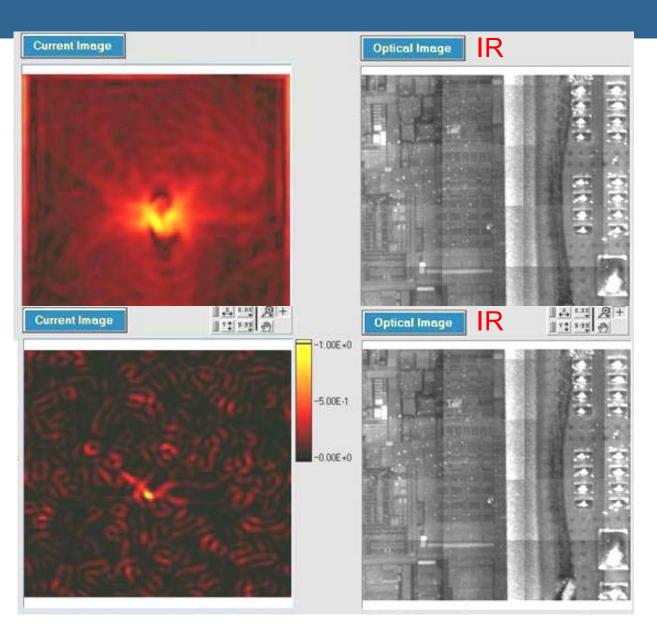
Current: 1 mA Distance: 1500 µm



SQUID at Package-Level (C4 bump)

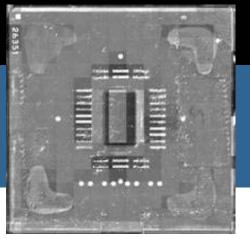
Current: 125 µA Distance: 450 µm

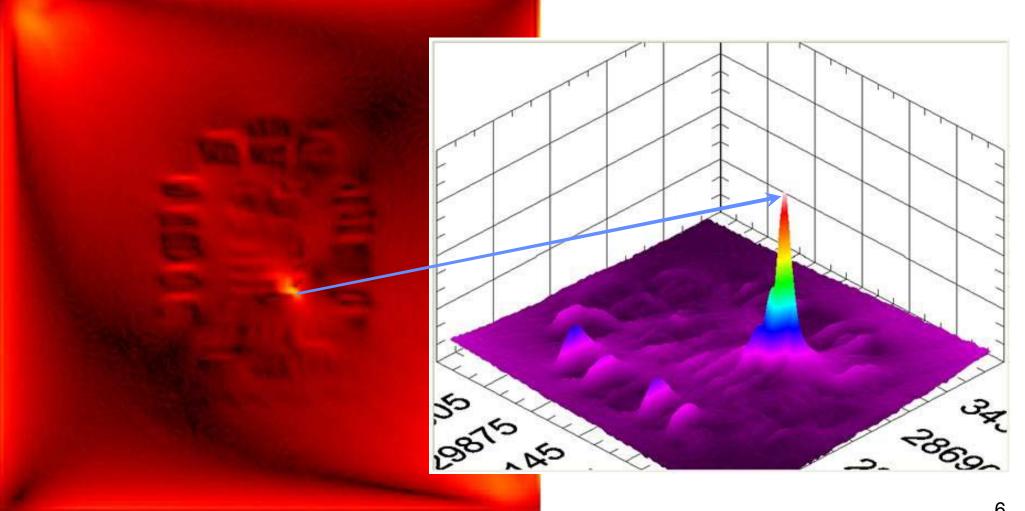
Current: 8.8 µA Distance: 450 µm





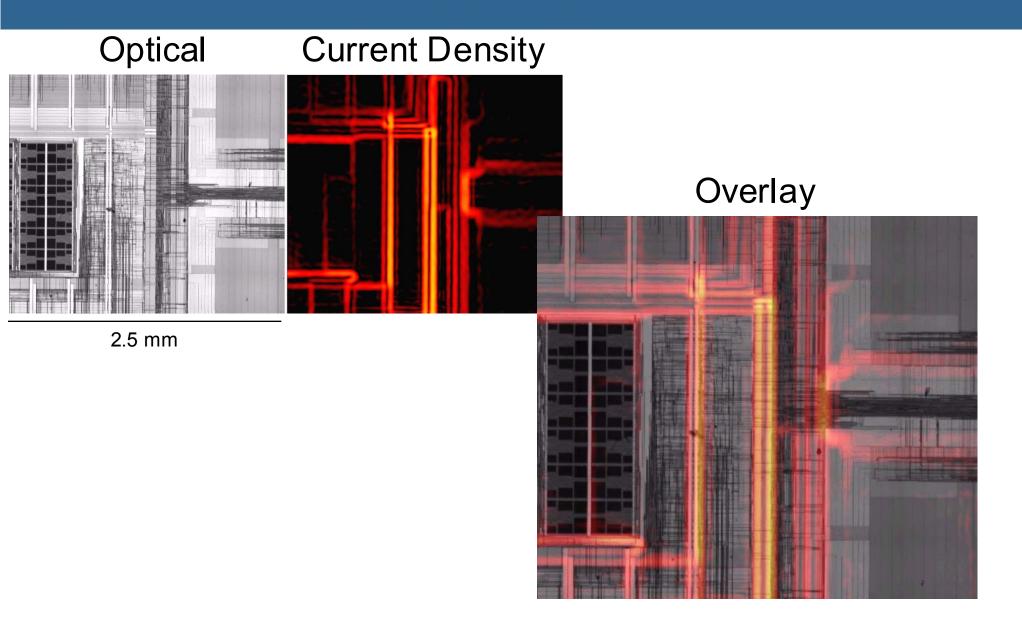
SQUID at Die-Level (back-side)







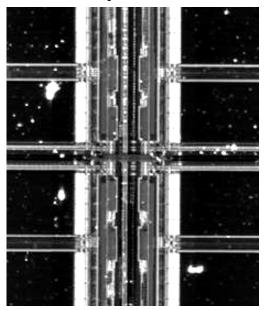
SQUID at Die-Level (front-side)





GMR at Die-Level (front-side)

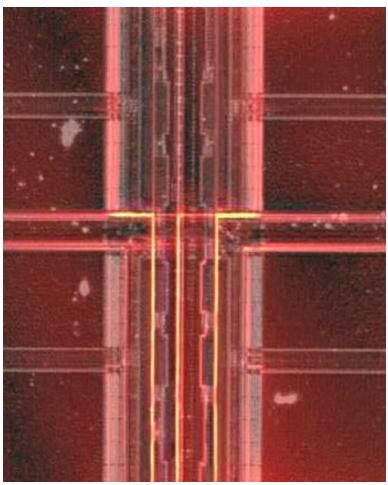
Optical



Current Density

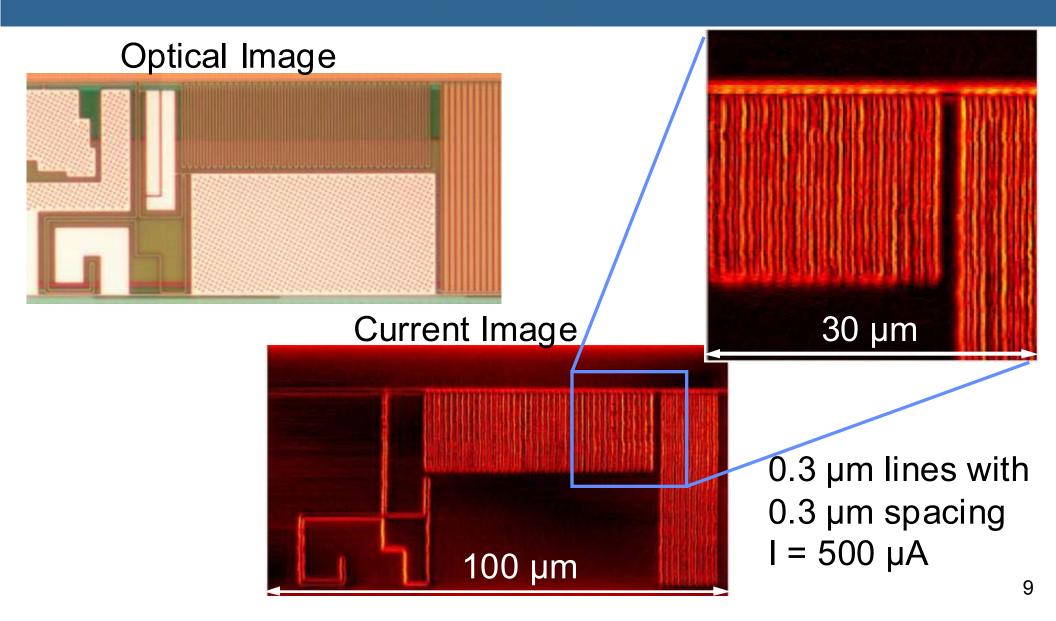


Overlay



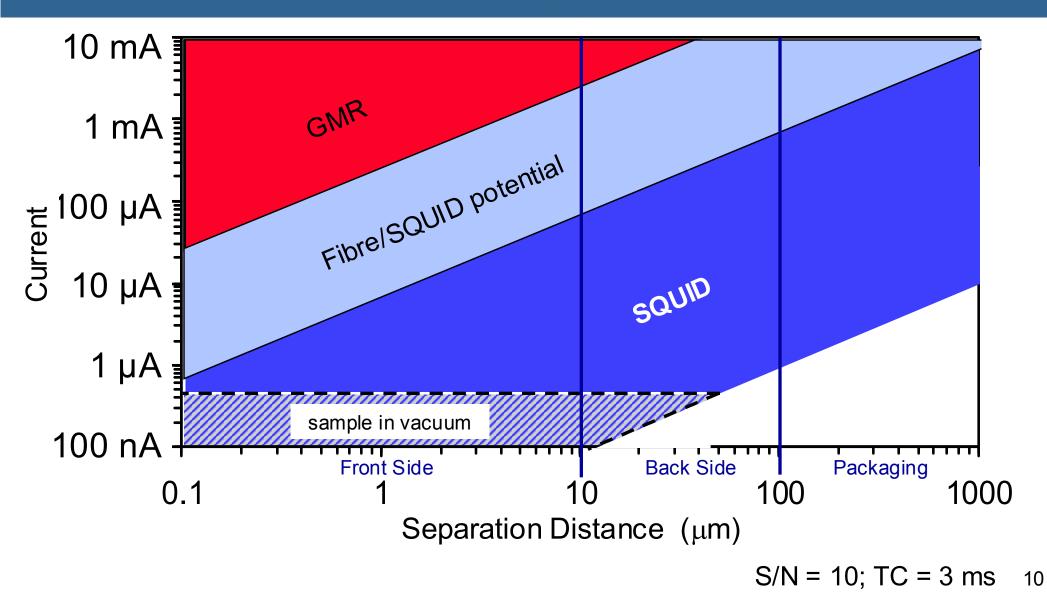


GMR at Die-Level (wafer part using probes)





Performance of Magnetic Sensors



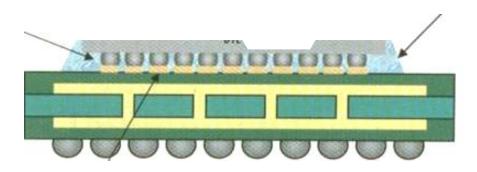


Comparison between sensors

- SQUID
 - Most sensitive
 - Ideal for large working distances \geq 100 µm
 - Localize defects to 3 µm
- Magnetoresitive (GMR)
 - Less sensitive than SQUID
 - Good for short working distances of a few microns
 - Sub-micron resolution when very close
- Fibre/SQUID
 - Less sensitive than SQUID, but can be better than GMR
 - Good for short working distances of a few microns
 - Natural high aspect ratio of tip is good for working in cavities
 - Sub-micron resolution when very close



Implementation Model



- Coarse scan with SQUID to isolate component
- If defect is in the die, then thin the die and fine scan with SQUID
- Locally open a cavity (laser; FIB)
- Scan with magnetoresistive sensor or fibre/SQUID.